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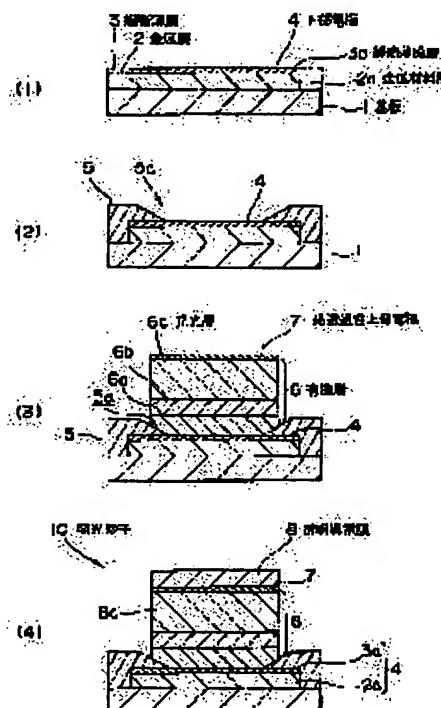
(54) LIGHT EMITTING ELEMENT AND ITS MANUFACTURING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a manufacturing method of a top surface light-emitting type light emitting element and the light emitting element wherein there is no leakage current and a stable light-emitting efficiency can be maintained.

SOLUTION: In the light emitting element 10 consisting of a lower part electrode 4 installed on a substrate 1, an organic layer 6 installed at the lower part electrode 4 and having at least a light emitting layer 6c, and a light permeating upper part electrode 7 installed on the organic layer 6, the lower part electrode 4 has a bilayered structure composed of a metallic material layer 2c and a buffer thin film layer 3c installed at an upper part of this metallic material layer 2c. The buffer thin film layer 3c is made to be composed of either a material whose electroconductivity is higher than

that of the organic layer 6 among oxides of the metallic material constituting the metallic material layer 2c or an oxide of chromium. By this, the lower part electrode 4 with the bilayered structure is made wherein a roughness of a surface of the metallic material layer 2c is moderated by the buffer thin film layer 3c, and an in-plane uniformity of a distance between the lower part electrode 4 and the light permeating upper part electrode 7 is secured.



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